

zQSFP+/QSFP28

TE Internal #: 2308171-4

zQSFP+, Cage Assembly with Integrated Connector, .8mm [.032in]

Centerline, Signal, Operating Temperature Range -40 – 85 °C [-40 –

185 °F]

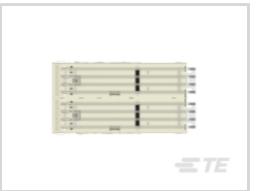
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Connectors > Pluggable IO Connectors & Cages











Form Factor: **zQSFP+**

Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Centerline (Pitch): .8 mm [.032 in]

Sealable: No

Circuit Application: Signal

Features

Product Type Features

Cage Type	Stacked
Form Factor	zQSFP+
Pluggable I/O Product Type	Cage Assembly with Integrated Connector
Sealable	No

Configuration Features

Number of Rear EONs per Port Column	0
Number of Positions	152
Number of Ports	4
Port Matrix Configuration	2 x 2

Contact Features

Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold (Au)
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	30 μm[.76 μin]



Termination Features

Termination Method to PCB	Through Hole - Press-Fit
Termination Post & Tail Length	2 mm[.079 in]

Housing Features

Cage Material	Nickel Silver Alloy
Centerline (Pitch)	.8 mm[.032 in]

Dimensions

PCB Thickness (Recommended)	3 mm[.118 in]

Usage Conditions

Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]

Operation/Application

Pluggable I/O Applications	QSFP28
Heat Sink Compatible	No
Circuit Application	Signal

Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Box & Tray	
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Other

Included Lightpipe	Yes
EMI Containment Feature Type	Internal/External EMI Springs

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900



ppm.

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | zQSFP+/QSFP28







Pluggable IO Connectors & Cages(424)

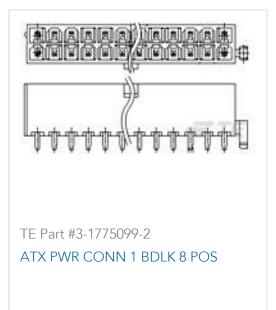
QSFP, QSFP+ & zQSPF+(424)

Customers Also Bought













TE Part #2-1734774-1
PCI EXP 3.1L 98 POS WHT 30u"











Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2308171-4_A1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2308171-4_A1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2308171-4_A1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English